



IEC 62453-303-1

Edition 1.0 2009-06

# INTERNATIONAL STANDARD

**Field device tool (FDT) interface specification –  
Part 303-1: Communication profile integration – IEC 61784 CP 3/1 and CP 3/2**



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IEC 61784 CP 3/1 and CP 3/2****FOREWORD**

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International Standard IEC 62453-303-1 been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This part, in conjunction with the other parts of the first edition of the IEC 62453 series cancels and replaces IEC/PAS 62453-1, IEC/PAS 62453-2, IEC/PAS 62453-3, IEC/PAS 62453-4 and IEC/PAS 62453-5 published in 2006, and constitutes a technical revision.

Each part of the IEC 62453-3xy series is intended to be read in conjunction with IEC 62453-2.

The text of this standard is based on the following documents:

FDIS	Report on voting
65E/127/FDIS	65E/140/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62453 series, under the general title *Field Device Tool (FDT) interface specification*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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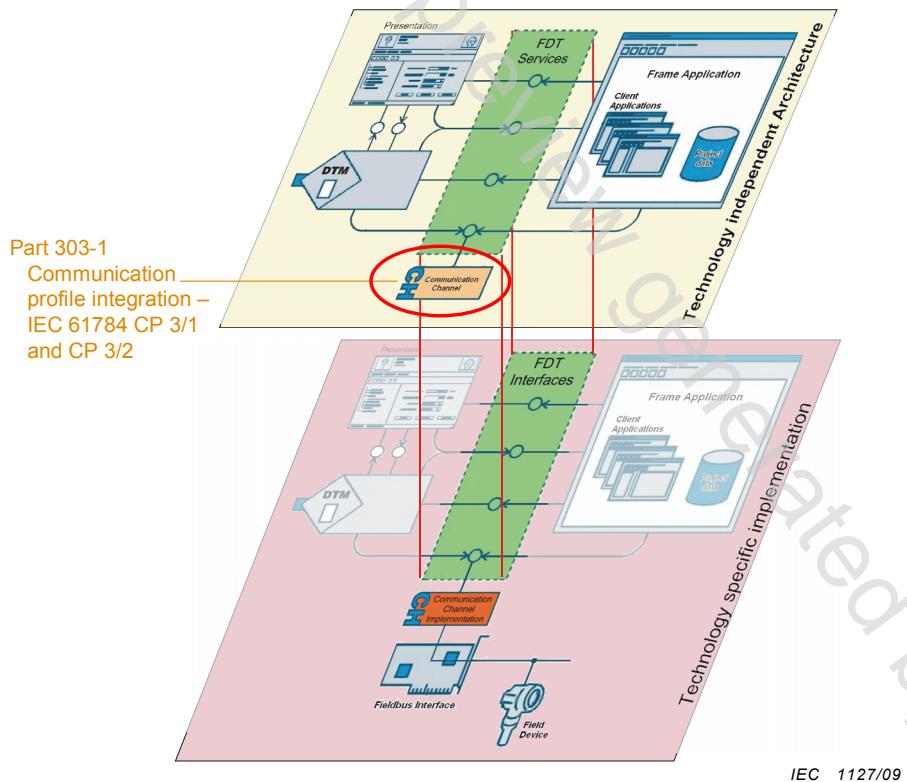
## INTRODUCTION

This part of IEC 62453 is an interface specification for developers of FDT (Field Device Tool) components for function control and data access within a client/server architecture. The specification is a result of an analysis and design process to develop standard interfaces to facilitate the development of servers and clients by multiple vendors that need to interoperate seamlessly.

With the integration of fieldbuses into control systems, there are a few other tasks which need to be performed. In addition to fieldbus- and device-specific tools, there is a need to integrate these tools into higher-level system-wide planning- or engineering tools. In particular, for use in extensive and heterogeneous control systems, typically in the area of the process industry, the unambiguous definition of engineering interfaces that are easy to use for all those involved is of great importance.

A device-specific software component, called DTM (Device Type Manager), is supplied by the field device manufacturer with its device. The DTM is integrated into engineering tools via the FDT interfaces defined in this specification. The approach to integration is in general open for all kinds of fieldbuses and thus meets the requirements for integrating different kinds of devices into heterogeneous control systems.

Figure 1 shows how IEC 62453–303-1 is aligned in the structure of the IEC 62453 series.



**Figure 1 – Part 303-1 of the IEC 62453 series**

**FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –****Part 303-1: Communication profile integration –  
IEC 61784 CP 3/1 and CP 3/2****1 Scope**

Communication Profile 3/1 and Communication Profile 3/2 (commonly known as PROFIBUS™<sup>1</sup>) defines communication profiles based on IEC 61158-2 Type 3, IEC 61158-3-3, IEC 61158-4-3, IEC 61158-5-3, and IEC 61158-6-3. The basic profiles CP 3/1 (PROFIBUS DP) and CP 3/2 (PROFIBUS PA) are defined in IEC 61784-1.

This part of IEC 62453 provides information for integrating the PROFIBUS protocol into the FDT interface specification (IEC 62453-2).

This part of the IEC 62453 specifies communication and other services.

This specification neither contains the FDT specification nor modifies it.

**2 Normative references**

The following referenced documents are indispensable for the application of this specification. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies

IEC 61131-3:2003, *Programmable controllers – Part 3: Programming languages*

IEC 61158 (all parts), *Industrial communication networks – Fieldbus specifications*

IEC 61158-2, *Industrial communication networks – Fieldbus specifications – Part 2: Physical layer specification and service definition*

IEC 61158-3-3, *Industrial communication networks – Fieldbus specifications – Part 3-3: Data-link layer service definition – Type 3 elements*

IEC 61158-4-3 *Industrial communication networks – Fieldbus specifications – Part 4-3: Data-link layer protocol specification – Type 3 elements*

IEC 61158-5-3: *Industrial communication networks – Fieldbus specifications – Part 5-3: Application layer service definition – Type 3 elements*

IEC 61158-6-3, *Industrial communication networks – Fieldbus specifications – Part 6-3: Application layer protocol specification – Type 3 elements*

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

<sup>1</sup> PROFIBUS™ is a trade name of the non-profit organization PROFIBUS Nutzerorganisation e.V. (PNO). This information is given for the convenience of users of this International Standard and does not constitute an endorsement by IEC of the trade name holder or any of its products. Compliance to this standard does not require use of the registered logos for PROFIBUS™. Use of the registered logos for PROFIBUS™ requires permission of PNO.

IEC 62453-1:2009, *Field Device Tool (FDT) interface specification – Part 1: Overview and guidance*

IEC 62453-2:2009, *Field Device Tool (FDT) interface specification – Part 2: Concepts and detailed description*

### **3 Terms, definitions, symbols, abbreviated terms and conventions**

#### **3.1 Terms and definitions**

For the purposes of this document, the terms and definitions given in IEC 62453-1 and IEC 62453-2 apply.

##### **3.1.1**

##### **bus interface module**

module of a field device that provides the connection to the fieldbus

##### **3.1.2**

##### **CP 3/1**

Communication profile of CPF3, featuring asynchronous transmission; RS 485 (ANSI TIA/EIA RS-485-A); optional RS 485-IS; plastic fiber; glass multi mode fiber or glass single mode fiber; PCF fiber

##### **3.1.3**

##### **CP 3/2**

Communication profile of CPF3, featuring synchronous transmission; manchester coded and bus powered (MBP); optional intrinsically safe (MBP-IS) and lower power (MBP-LP)

#### **3.2 Symbols and abbreviated terms**

For the purposes of this document, the symbols and abbreviations given in IEC 62453-1, IEC 62453-2 and the following apply.

BIM Bus Interface Module

BMCP Bus Master Configuration Part

GSD General Station Description

#### **3.3 Conventions**

##### **3.3.1 Data type names and references to data types**

The conventions for naming and referencing of data types are explained in IEC 62453-2, Clause A.1

##### **3.3.2 Vocabulary for requirements**

The following expressions are used when specifying requirements.

Usage of “shall” or “mandatory”

No exceptions allowed.

Usage of “should” or “recommended”

Strong recommendation. It may make sense in special exceptional cases to differ from the described behaviour.

Usage of “can” or “optional”

Function or behaviour may be provided, depending on defined conditions.

##### **3.3.3 Use of UML**

Figures in this document are using the UML notation as defined in Annex A of IEC 62453-1.